

MODULE HAVING DUAL-BAND SURFACE ACOUSTIC WAVE
CIRCUITS AND METHOD OF MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

A module that contains multiple surface acoustic wave (SAW)
circuits and a method of manufacturing the module. In one
embodiment, the module includes: (1) a hermetically-sealable shell
having first and second terminal sets, (2) a first SAW circuit,
located within the shell and couplable to the first terminal set,
that filters signals in a first band of communications frequencies,
and (3) a second SAW circuit, located within the shell and
couplable to the second terminal set, that filters signals in a
second band of communications frequencies.